

Dev Shah

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EXPERIENCE

Amazon, San Francisco

Jan '24 – Present

Product Design Engineer

- Lead and 1st PDE at [Bee.computer](#), an ambient AI wearable startup acquired by Amazon.
- Lead PDE for 2K & 4K Ring/Blink smart home security Camera & Doorbell (**10M+ volume**).
- Drove integration across **RF, Optics, PCBA, thermal, battery, and ID**.
- Applied **DFM/DFA, GD&T**, and **statistical tolerance analysis** to hit quality with speed.
- Conducted **FEA** on critical features and sub-systems to converge on robust margins.
- Supported **EVT/DVT** at CMs in **Vietnam, Malaysia & China**.

Amazon Robotics, Boston

July '23 – Dec '23

Hardware Development Engineer Co-op

- Designed novel center-of-gravity test equipment to optimize robot stability/maneuverability.
- **Automated image-quality test stations** for 2D/3D cameras: **reduced test time 300s → 30s**.

Mediscient Devices Pvt. Ltd., India

Feb '20 – July '22

R&D Team Lead - Mechanical Engineer

- Developed a patent-pending [wearable insulin injector](#) (<10 dollars BOM).
- Built [Needle-Safe autoinjector](#) for high-viscosity drugs; led team of 7 as first full-time hire.

Beyond2D, India

Apr '20 – June '22

Founder & Technical Lead

- Built biocompatible **3D-printing & 3D-scanning** facility for dental applications; delivered to 20+ clinics; exited with **900% ROI**.

EDUCATION & CERTIFICATIONS

University of California, San Diego

Sept '22 – Dec '23

MS in Mechanical Engineering + MicroMBA | GPA 3.93/4.00

- Graduate Researcher, Poulidakos Lab: nature-inspired 3D nano-metasurfaces (<50 nm features); [paper: 3D-Architected gratings for polarization-sensitive structural color](#).
- Teaching Assistant: MAE156A Mechanical Design I; MAE180A Spacecraft Design.

Pandit Deendayal Energy University, India

June '17 – May '21

B. Tech in Mechanical Engineering | GPA 9/10

Project Management Professional (PMP)® - Issued by PMI – [Link](#)

Issued: Aug '24

CORE SKILLS

- **Core PDE:** DFM/DFA, GD&T (ASME Y14.5), tolerance stacks (statistical), FEA, FA/RCA, build reports, supplier interface, EVT/DVT
- **Camera systems:** optics integration (lens/sensor stack), camera module packaging, thermal interfaces, stray-light & baffling (if applicable), sealing/IP for outdoor use.
- **Manufacturing:** injection molding, die casting, stamping, CNC, USW, adhesives, gasketing, O-rings, snaps/bosses, thread-forming, design for assembly.
- **Tooling/Quality:** CMs in VN/MY/CN, process capability/CPK